

## **Amendments to the Claims**

Claims 1-36 (Canceled).

37. (previously presented): A substrate susceptor for physically supporting a semiconductor substrate to be deposited upon, the susceptor comprising a body having a front substrate receiving side face comprising a bearing surface to physically contact and support the semiconductor substrate to be deposited upon, a back side face, and a peripheral edge; the body comprising a ring and a radial inner portion at least a radial majority of which is non-solid space extending from the front side face to the back side face, the bearing surface being received on said ring, the susceptor comprising one or more extensions extending from said ring into the radially inner portion such that only a portion of the radial inner portion is non-solid space, the susceptor comprising at least one cross piece extending across the radial inner portion.

38. (Canceled).

39. (Previously presented): The substrate susceptor of claim 37 wherein said cross piece is opaque to infrared radiation.

40. (Previously presented): The substrate susceptor of claim 37 wherein said cross piece is transparent to infrared radiation.

41. (Previously presented): The substrate susceptor of claim 37 comprising at least two cross pieces extending across the radial inner portion.

42. (Previously presented): The substrate susceptor of claim 41 wherein said cross pieces are opaque to infrared radiation.

43. (Previously presented): The substrate susceptor of claim 41 wherein said cross pieces are transparent to infrared radiation.